

# ON Semiconductor

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# Schottky Barrier Diodes

## RB751S40

### Features

- Low Forward Voltage Drop
- Fast Switching
- Very Small and Thin SMD Package
- Profile Height, 0.43 mm Max
- Footprint, 1.0 x 0.6 mm

### ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Maximum Repetitive Reverse Voltage	$V_{RRM}$	30	V
Average Rectified Forward Current	$I_{F(AV)}$	30	mA
Forward Surge Current (8.3 mS Single Half Sine-Wave)	$I_{FSM}$	200	mA
Power Dissipation	$P_D$	227	mW
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	°C

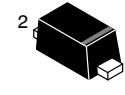
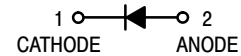
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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### CONNECTION DIAGRAM



**SOD-923  
CASE 514AB**

### MARKING DIAGRAM



AD = Specific Device Code  
M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
RB751S40P2T5G	SOD-923 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**THERMAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	550	$^{\circ}C/W$

1. Minimum land pad.

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$  unless otherwise noted)

Characteristic	Symbol	Test Conditions	Min	Max	Unit
Breakdown Voltage	$V_R$	$I_R = 10 \mu A$	30	-	V
Forward Voltage	$V_F$	$I_F = 1 \text{ mA}$	-	370	mV
Reverse Leakage	$I_R$	$V_R = 30 \text{ V}$	-	0.5	$\mu A$
Reverse Recovery Time	$t_{rr}$	$I_F = I_R = 10 \text{ mA}$ , irr = 0.1 $I_R$	-	8.0	nS
Junction Capacitance	$C_j$	$V_R = 1 \text{ V}$ , $f = 1.0 \text{ MHz}$	-	2.5	pF

**TYPICAL PERFORMANCE CHARACTERISTICS**

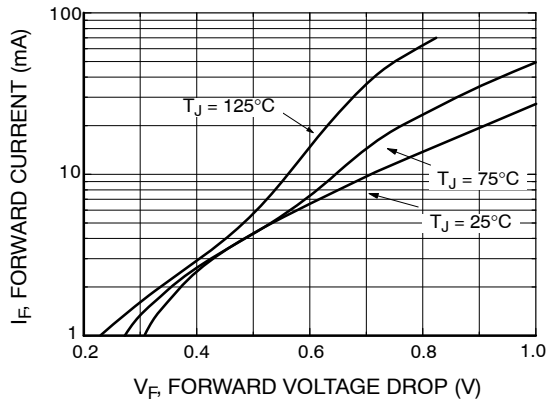


Figure 1. Forward Current Characteristics

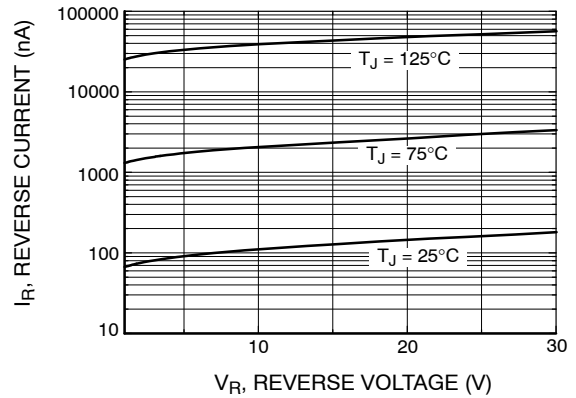


Figure 2. Reverse Leakage Current

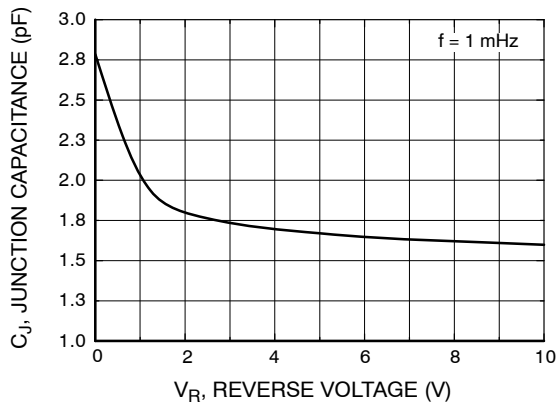


Figure 3. Junction Capacitance

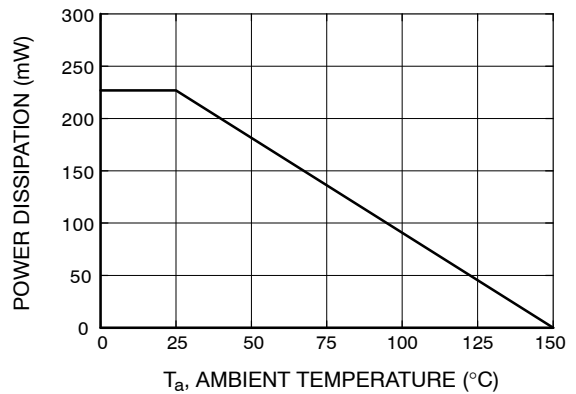


Figure 4. Power Derating